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# Table of Contents

**Preface**

**Simulation of Polymer Removal from a Powder Injection Molding Compact by Thermal Debinding**
S. Ying, Y.C. Lam, S.C.M. Yu and K.C. Tam 1

**Singularity of Interface Stresses in Fibre Push-Out Test**
J.H. Park, Y. Dai and J.K. Kim 7

**A Self-Consistent Scheme for Asperity Contact**
H. Fan and K.Y. Sze 17

**Microstructural Influences on Inhomogeneous Deformation in Superplastic Ti-6Al-4V**
T.W. Kim and N.S. Choi 23

**Novel Methods to Measure Residual Stresses in Thin Films**
T.Y. Zhang 31

**The Root Angle in Elastoplastic Peeling Tests**
Z. Chen 41

**Fracture Toughening Analysis of Shape Memory Alloys**
S. Gao and S. Yi 49

**Finite Element Modelling Damage in Brittle Matrix Composites**
J. Chia and J.W. Hancock 55

**Popcorn Failure and Unstable Void Growth in Plastic Electronic Packages**
C.W. Chong, T.F. Guo and L. Cheng 61

**Three-Dimensional Modeling of Coordination Number and Contiguity in the Incipient Stage of Liquid Phase Sintering**
P. Liu and D.X. Wang 67

**Micromechanical Modeling of Granular Materials Using Three Dimensional Discrete Element Modeling**
T.G. Sitharam and S.V. Dinesh 73

**A Constitutive Equation for Viscoelastic Porous Gels during Drying Process**
B. Wang, Y. Liu and Z. Xiao 79

**A Thermodynamic Model of the BCC  FCC Polymorphic Change in Niobium due to Nanocrystallization by Mechanical Milling**
P.P. Chattopadhyay and I. Manna 87

**The Modeling and Determination of Dynamic Elastic Modulus of Metal Matrix Composites**
N. Srikanth and M. Gupta 93

**Micro-Macro Combined Study for a Porous Constitutive Model Based on the Analysis of a Cylindrical Void**
B. Chen, Z.H. Gao, X.H. Peng, J.H. Fan and C. Cai 101

**New Materials for Magnetic Refrigerator Applications**
R. Nirmala, V. Sankaranarayanan, K. Sethupathi and A.V. Morozkin 113

**Dynamic Properties of Magnetorheological Materials**
W.H. Li, G. Chen, S.H. Yeo and H. Du 119

**Molecular Dynamics Simulations of Hydrogen Embrittlement of a Single Crystal of Nickel by the Embedded Atom Method**
X.J. Xu, M. Wen, S. Fukuyama and K. Yokogawa 125

**Nanoscale Friction and Interfacial Effects**
T. Kawaguchi and H. Matsukawa 133

**Scaling Behavior of Dynamic Hysteresis in Multi-Domain Spin Systems**
J.M. Liu, X.Y. Chen, H.L.W. Chan and C.L. Choy 139

**Scaling Property of Hysteresis Dispersion in Spin Systems**
J.M. Liu, X.Y. Chen, H.L.W. Chan and C.L. Choy 145

**Atomistic Simulation of the Core Structure of 90° Partial Dislocation in Silicon: A Burgers Vector Perspective**
Z.M. Choo, M.H. Liang and S. Li 151

**EPR Spectroscopy, Powder EPR Lineshape Simulation Technique in Rigid-Lattice and Slow-Motional Regime: An Application to $V_2O_5$-Based Glass**
B.B. Das 157

**Computer Modelling of the Structures, Stabilities and Thermoelectric Efficiency of Materials with Clathrate Structures**
J.S. Tse, K. Uehara, Z.Q. Li, R. Rousseau and D.D. Klug 163

**Quantum Confinement and Excitonic Effects in Vertically Coupled Quantum Dots**
X. Xu and Y.P. Feng 171

**Computational Study of GaAs Microclusters**
T.B. Boo, H.H. Kwong and Y.P. Feng 177

**Shear-Induced Particle Migration in a Pressure Driven Tube Flow**
X. Chen, Y.C. Lam, K.W. Tan, M. Jan, K.C. Tam and S.C.M. Yu 183

**A Multi-Scale Analysis for Size-Dependent Indentation Microhardness**
Y.X. Gao and H. Fan 189

**New Techniques to Study Materials: Application of Synchrotron X-Ray, CCD-Instruments and Lasers**
S.K. Saxena 195

**Improvement of Material Characterization of Curing Polymers by Image Processing**
V. Gonda, C.J. Liu, C. van't Hof, L.J. Ernst and G.Q. Zhang 205

**Damping Characterization of Aluminium Based Composites Using an Innovative Circle-Fit Approach**
N. Srikanth and M. Gupta 211

**Determination of Sintering Stress on the Densification of Micron-Sized Alumina**
Z.M. He and J. Ma 217

**Interfacial Microstructure of Solid-State Diffusion Bonded Inconel Alloy 718**
G.G. Zhang, R.S. Chandel, H.P. Seow and H.H. Hng 223

**Coupled Finite Element Thermal and Structural Analysis**
T.F. Lam 229

**Finite Element Analysis as a Tool for the Investigation of Backward Cup Extrusion**
U.R. Krishna and H.S. Valberg 235

**Simulation and Design Optimisation of Micro Pumps**
Y. Xu, C.W. On, Y. Kui, E.H.T. Francis, X.X. Zhang, K.Y. Peng and W.P. Wang 241

**Web Based Process and Material Selection for MEMS Design and Manufacturing**
X.F. Zha and H. Du 247

**On Modelling of Biodegradable Foams for Packaging Applications**
B. Wang, J. Song and Y. Kang 253

**The Role of Ab Initio Electronic Structure Calculations in Contemporary Materials Science**
M. Šob, M. Friák, L.G. Wang and V. Vitek 261